

Product Summary

V_{BR} Min	I_{PP} Max	C_T Typ
13.3V	13A	80pF

Description

This new generation TVS is designed to protect sensitive electronics from damage due to ESD. The combination of small-size and high ESD surge capability makes it ideal for use in portable applications such as cellular phones, digital cameras, and MP3 players.

Applications

- Cellular Handsets
- Portable Electronics
- Computers and Peripherals

Features

- Low Profile Package (0.53mm max) and Ultra-small PCB Footprint Area (1.08mm x 0.68mm max) Suitable for Compact Portable Electronics
- Provides ESD Protection per IEC 61000-4-2 Standard: Air ±30kV, Contact ±30kV
- One Channel of ESD Protection
- Low Channel Input Capacitance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: X1-DFN1006-2 with Sidewall Plating
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.001 grams (Approximate)

X1-DFN1006-2



Bottom View



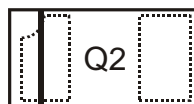
Device Schematic

Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
D12V0H1U2LP-7B	Standard	Q2	7	8	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



Q2 = Product Type Marking Code
Line Denotes Pin 1 or Cathode Side

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P _{PP}	300	W	8/20μs, per Figure 3
Peak Pulse Current	I _{PP}	13	A	8/20μs, per Figure 3
ESD Protection—Contact Discharge	V _{ESD_Contact}	±30	kV	IEC 61000-4-2 Standard
ESD Protection—Air Discharge	V _{ESD_Air}	±30	kV	IEC 61000-4-2 Standard

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P _D	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Working Voltage	V _{RWM}	—	—	12.0	V	—
Reverse Current (Note 6)	I _R	—	2	50	nA	V _R = V _{RWM} = 12.0V
Reverse Breakdown Voltage	V _{BR}	13.3	—	15.75	V	I _R = 1mA
Reverse Clamping Voltage	V _{CL}	—	—	19	V	I _{PP} = 5A, t _p = 8/20μs
		—	—	23		I _{PP} = 13A, t _p = 8/20μs
Capacitance	C _T	—	80	95	pF	V _R = 0V, f = 1MHz

- Notes:
- Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 - Short duration pulse test used to minimize self-heating effect.

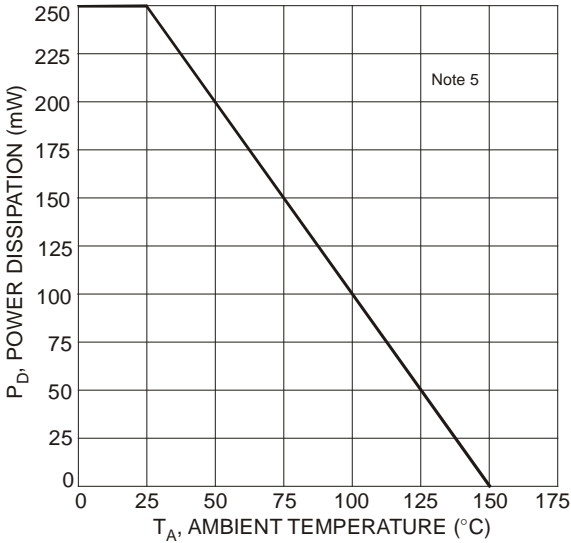


Figure 1 Power Derating Curve

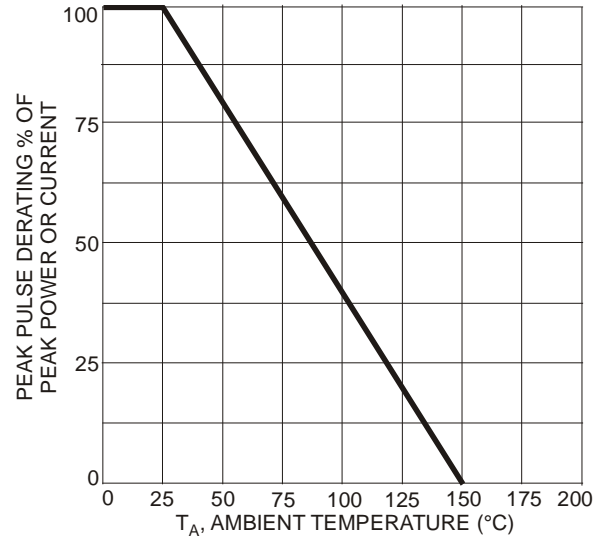


Figure 2 Pulse Derating Curve

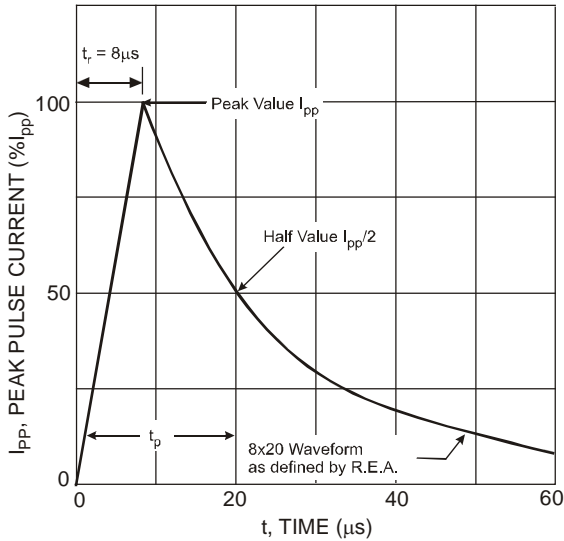


Figure 3 Typical 8 x 20µs Pulse Waveform

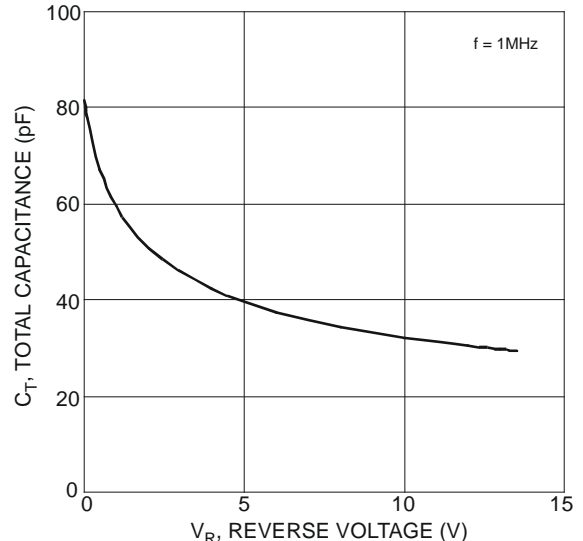


Figure 4 Typical Capacitance

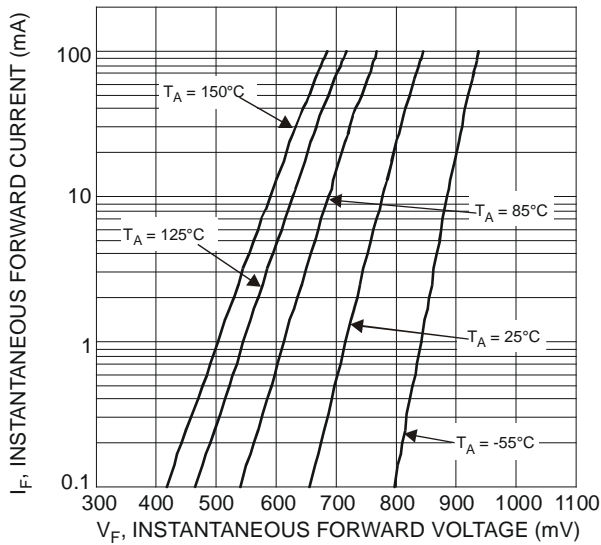


Figure 5 Typical Forward Characteristics

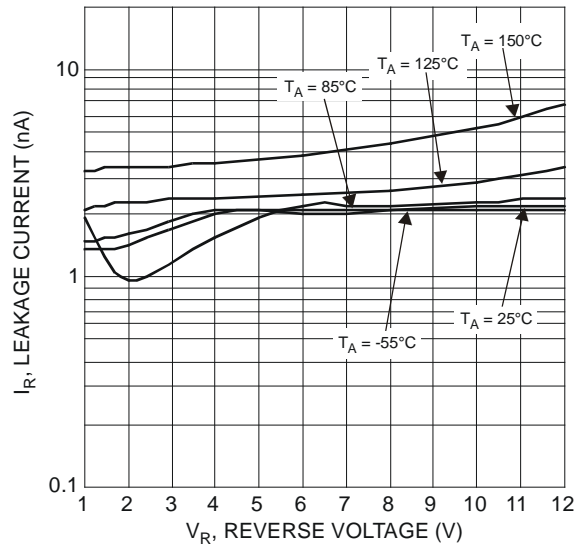
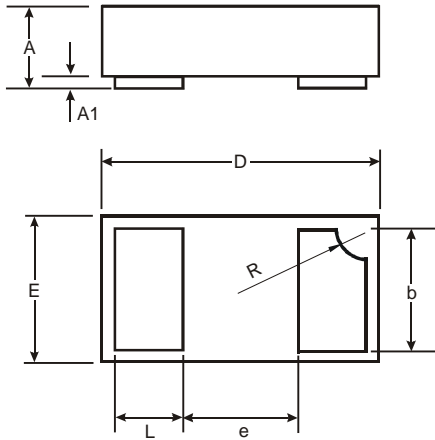


Figure 6 Typical Reverse Characteristics

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1006-2

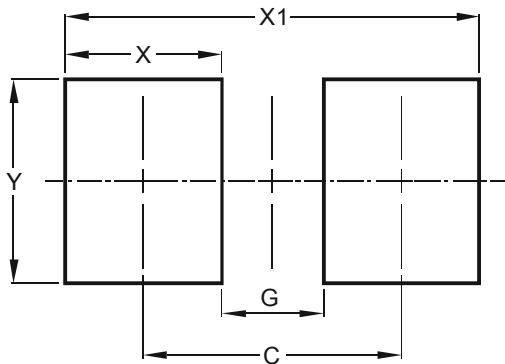


X2-DFN1006-2			
Dim	Min	Max	Typ
A	0.34	0.4	0.37
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	—	—	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1006-2



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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